Product/Process Change Notice - PCN 2377 -

AnalogDevices, Inc. One Analog Way, Wilmington, MA01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.**ADI contact information is listed below.

PCN Title:	Additional BOM for ADI products MAX17553/MAX17554/MAX17645 products (TDFN/T822C+6C for QP02/QP03)
Publication Date:	05-Jul-2023
Effectivity Date:	*07-Oct-2023 (the earliest date that a customer could expect to receive changed material)*
Revision Description:	

Description Of Change:

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MAX17553/MAX17554/MAX17645

Existing BOM at current assembler UTAC THAI LIMITED/THAILAND (UTL)

a. Die attach: 8006NS (non-conductive)

b. Bond wire material: gold (Au)

Reason For Change:

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a. Qualifying mainstream die attach material

b. The conversion to CuPd wire aligns with industry trends and ADI's current and future alignment with copper wire.

Note 1: UTL has been manufacturing CuPd wire products for ADI in mass production for several years.

A Reliability report is attached (ref. R43128CQ_UTL_Cu).

There are no regulatory compliance changes to the material content of the devices.

There are no changes to Form/Fit/Function of these devices.

Impact of the change (positive or negative) on fit, form, function & reliability:

Product Identification (this section will describe how to identify the changed material):

Summary of Supporting Information:

Supporting Documents:

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

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Appendix A - Impacted items, see csv PN listing in PCN Zip file